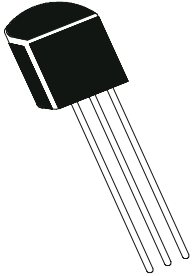


NPN/PNP SILICON PLANAR EPITAXIAL TRANSISTORS

**MPSA05,MPSA06
MPSA55,MPSA56**

**TO-92
Plastic Package**



Amplifier Transistors

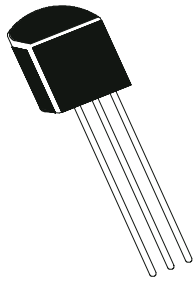
ABSOLUTE MAXIMUM RATINGS(Ta=25°C unless otherwise specified)

DESCRIPTION	SYMBOL	MPSA05 MPSA55	MPSA06 MPSA56	UNITS
Collector Emitter Voltage	V_{CEO}	60	80	V
Collector Base Voltage	V_{CBO}	60	80	V
Emitter Base Voltage	V_{EBO}		4	V
Collector Current Continuous	I_C		500	mA
Total Device Dissipation@Ta=25°C	P_D		625	mW
Derate Above 25°C			5.0	mW/°C
Total Device Dissipation@ Tc=25°C	P_D		1.5	W
Derate Above 25°C			12	mW/°C
Operating And Storage Junction Temperature Range	T_j, T_{stg}		-55 to +150	°C
THERMAL RESISTANCE				
Junction to ambient	$R_{th(j-a)} (1)$		200	°C/mW
Junction to case	$R_{th(j-c)}$		83.3	°C/mW

(1) $R_{th(j-a)}$ is measured with the device soldered into a typical printed circuit board.

NPN SILICON PLANAR EPITAXIAL TRANSISTORS

**MPSA05, MPSA06
MPSA55, MPSA56**



**TO-92
Plastic Package**

ELECTRICAL CHARACTERISTICS (Ta=25°C Unless Otherwise Specified)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
Collector Emitter Voltage	V_{CEO}^*	$I_C=1mA, I_B=0$				
	MPSA06/56		80			V
Emitter-Base Voltage	V_{EBO}	$I_E=100\mu A, I_C=0$	4.0			V
Collector-Cut off Current	I_{CBO}					
	MPSA06/56				0.1	μA
Collector-Cut off Current	I_{CEO}	$V_{CE}=60V, I_B=0$			0.1	μA
Collector-Emitter (sat) Voltage	$V_{CE(sat)}$	$I_C=100mA, I_B=10mA$			0.25	V
Base-Emitter(on) Voltage	$V_{BE(on)}$	$I_C=100mA, V_{CE}=1V$			1.2	V
DC Current Gain	h_{FE}	$V_{CE}=1V, I_C=10mA$	100			
			100			
		$V_{CE}=1V, I_C=100mA$				

ELECTRICAL CHARACTERISTICS (Ta=25°C Unless Otherwise Specified)

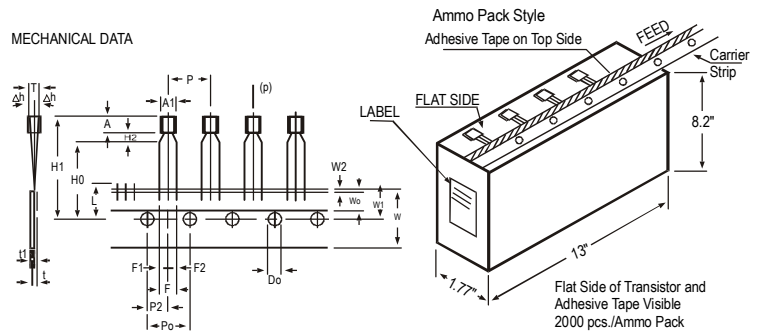
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
DYNAMIC CHARACTERISTICS					
Transition Frequency	NPN	f_T^{**}	$I_C=10mA, V_{CE}=2V$	100	MHz
	PNP		$I_C=100mA, V_{CE}=1V$	50	MHz
			$f=100MHz$		
			$f=100MHz$		

*Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

** f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

TO-92 Plastic Package

TO-92 Transistors on Tape and Ammo Pack

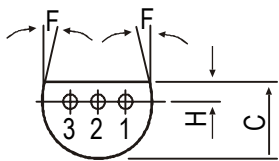
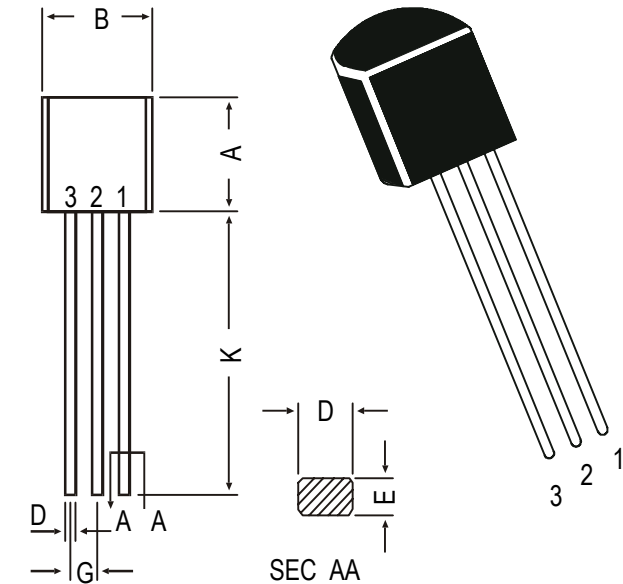


All dimensions in mm unless specified otherwise

ITEM	SYMBOL	SPECIFICATION				REMARKS
		MIN.	NOM.	MAX.	TOL.	
BODY WIDTH	A1	4.0		4.8		
BODY HEIGHT	A	4.8		5.2		
BODY THICKNESS	T	3.9		4.2		
PITCH OF COMPONENT	P		12.7		±1	
FEED HOLE PITCH	Po		12.7		±0.3	CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH
FEED HOLE CENTRE TO COMPONENT CENTRE	P2		6.35		±0.4	TO BE MEASURED AT BOTTOM OF CLINCH
DISTANCE BETWEEN OUTER LEADS	F		5.08		+0.6 -0.2	
COMPONENT ALIGNMENT	Δh		0	1		AT TOP OF BODY
TAPE WIDTH	W		18		±0.5	
HOLD-DOWN TAPE WIDTH	Wo		6		±0.2	
HOLE POSITION	W1		9		+0.7 -0.5	
HOLD-DOWN TAPE POSITION	W2		0.5		±0.2	
LEAD WIRE CLINCH HEIGHT	Ho		16		±0.5	
COMPONENT HEIGHT	H1			23.25		
LENGTH OF SNIPPED LEADS	L			11.0		
FEED HOLE DIAMETER	Do		4		±0.2	
TOTAL TAPE THICKNESS	t			1.2		t1 0.3 - 0.6
LEAD - TO - LEAD DISTANCE F1,	F2		2.54		+0.4 -0.1	
CLINCH HEIGHT	H2			3		
PULL - OUT FORCE	(P)	6N				

NOTES

1. MAXIMUM ALIGNMENT DEVIATION BETWEEN LEADS NOT TO BE GREATER THAN 0.2 mm.
2. MAXIMUM NON-CUMULATIVE VARIATION BETWEEN TAPE FEED HOLES SHALL NOT EXCEED 1 mm IN 20 PITCHES.
3. HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO EXPOSURE OF ADHESIVE.
4. NO MORE THAN 3 CONSECUTIVE MISSING COMPONENTS ARE PERMITTED.
5. A TAPE TRAILER, HAVING AT LEAST THREE FEED HOLES ARE REQUIRED AFTER THE LAST COMPONENT.
6. SPLICES SHALL NOT INTERFERE WITH THE SPROCKET FEED HOLES.



- PIN CONFIGURATION**
1. COLLECTOR
 2. BASE
 3. EMITTER

All dimensions in mm.

DIM	MIN.	MAX.
A	4.32	5.33
B	4.45	5.20
C	3.18	4.19
D	0.41	0.55
E	0.35	0.50
F	5 DEG	
G	1.14	1.40
H	1.14	1.53
K	12.70	—

Packing Detail

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5.0K	17" x 15" x 13.5"	80.0K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2.0K	17" x 15" x 13.5"	32.0K	12.5 kgs

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Discrete Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished on the CDIL Web Site/CD is believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Discrete Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



CDIL is a registered Trademark of

Continental Device India Limited

C-120 Naraina Industrial Area, New Delhi 110 028, India.

Telephone + 91-11-579 6150 Fax + 91-11-579 9569, 579 5290

e-mail sales@cdil.com www.cdil.com